AMENDMENTS TO THE CLAIMS

The following is a complete, marked up listing of revised claims with a status identifier in parentheses, underlined text indicating insertions, and strikethrough and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1. (Currently Amended) A method to compensate for process variations when printing a pattern on a workpiece, said method comprising:

determining a two-dimensional <u>critical dimension (CD) profile distribution</u> [[in]] associated with said pattern printed on said workpiece,

generating a two-dimensional compensation file to equalize fluctuations <u>variations</u> in said two-dimensional CD—<u>profile</u> <u>distribution</u>, and

patterning a workpiece [[with]] using said two-dimensional compensation file.

- 2. (Currently Amended) The method of claim 1, wherein said determining includes predicting the two-dimensional CD profile distribution.
- 3. (Currently Amended) The method of claim 1, wherein said determining includes measuring the two-dimensional CD profile distribution.
- 4. (Original) The method of claim 1, wherein said two-dimensional compensation file includes pattern data.

- 5. (Original) The method of claim 1, wherein said two-dimensional compensation file includes dose compensation data.
- 6. (Original) The method of claim 1, wherein said two-dimensional compensation file is a correction map.
- 7. (Original) The method of claim 1, wherein said two-dimensional compensation file is a two-dimensional dose compensation profile.
- 8. (Currently Amended) A method to compensate for process variations when printing a pattern on a workpiece, said method comprising:

determining a two-dimensional <u>critical dimension (CD) profile distribution</u> [[in]] associated with said pattern printed on said workpiece,

generating a two-dimensional dose compensation profile to equalize fluctuations

variations in said two-dimensional CD—profile distribution, and

patterning a workpiece [[with]] using said two-dimensional dose compensation profile.

9. (Currently Amended) A method to compensate for process variations when printing a pattern on a workpiece, said method comprising:

predicting a two-dimensional <u>critical dimension (CD)</u> profile <u>distribution</u> [[in]] <u>associated</u> with said pattern to be printed on said workpiece,

generating a two-dimensional dose compensation profile to equalize fluctuations variations in said [[2-dim]] <u>two-dimensional</u> CD—<u>profile</u> <u>distribution</u>,

patterning the workpiece [[with]] <u>using said [[2-dim]] two-dimensional</u> dose compensation profile.

10. (New) An apparatus for process variation compensation when printing a pattern on a workpiece, said apparatus comprising:

a measuring device for determining a two-dimensional critical dimension (CD) distribution associated with said pattern printed on said workpiece and generating a two-dimensional compensation file to equalize variations in said two-dimensional CD distribution; and

a writing device for patterning a workpiece using said two-dimensional compensation file.